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National Aerospace Laboratory NLR



















AMS Tracker Thermal Control Subsystem HX_WireHeater_Solder_Procedure

AMSTR-NLR-PR-055 ISSUE 01 25 SEPT 2008

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Summary

This document describes the Heat eXchanger wire heater solder procedure. The solder procedure is part of the FM/QM HX manufacturing sequence.













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1 Scope of the document

The procedure in this document describes the solder procedure of the wire heaters to the FM/QM Heat eXchanger .

The procedure defines the temperatures and the sequence of steps.

2 References documents

	Title	Number	Date
RD-1			
RD-2			



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3 Heat eXchanger

The Heat eXchanger is part of the TTCB as shown in Figure 3-1.

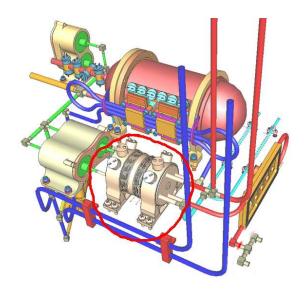


Figure 3-1: TTCS TTCB

The Heat eXchanger is depicted in Figure 3-2. The outside of the HX consist of an Inconel body with 2 grooves. Into each groove a Inconel wire heater shall be soldered.



Figure 3-2: TTCS Heat eXchanger



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4 Solder procedure

4.1 Materials needed

Heat eXchanger

Inconel heater Thermocoax alloy 600, type ZEZI 10/10-128-10/2xCM10 SPE/CEMENT8/1419

WHITE/200 mm

Solder Sn89Ag6Pb5,

Flux Lötöl ST

Hot plate T \approx 240 °C

Solder iron T \approx 393 °C

Clamp tool (AIDC)

IPA

Sandblast equipment

Sandpaper / Scotch Brite

4.2 Procedure description

Before each solder action the surfaces must be clean. The HX shall be cleaned by sandblasting and wiping with IPA wetted tissue. During cleaning process contamination of the HX inside must be prevented, tubes shall always be closed with caps.

Two wire heaters shall be soldered to the HX, first the heater on section 1, while the grooves of section 2 are shielded with kapton tape to prevent contamination with flux and solder (see figure 4.1 HX solder set-up).

The wire heater shall be cleaned by using sandpaper and Scotch Brite, finished by wiping with IPA wetted cloth



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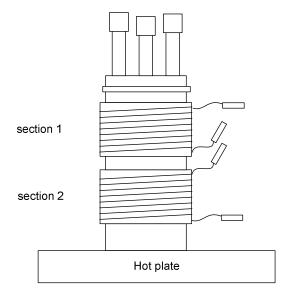


Figure 4-1: HX solder set-up

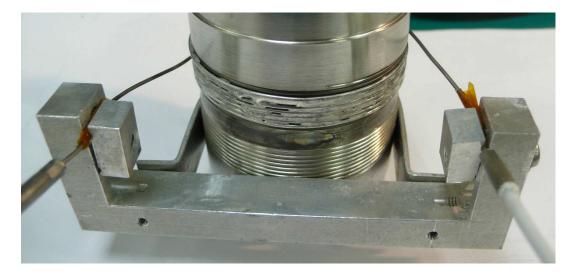


Figure 4-2: Clamp tool

















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4.3 Wire heater solder procedure in steps

Test sampl	Test sample indication: Test engineer:		Test Date:	
Step	Action to be taken	Result		
1.	Section 1	Section 1		
2.	Switch on hot plate, set $T \approx 240$	PC .		
3.	Measure length of wire heater an	d length of cold ends		
4.	Measure resistance of wire heate	$r(R \approx 15 \Omega)$		
5.	Cut thin wire OD≤ 0.5 mm to ler	igth of wire heater		
6.	Sandblast HX solder section 1, p	rotect HX other sections with tape, to prevent sandblasting total HX		
7.	Remove sand with compressed a	ir		
8.	Clean groove with tissue and IPA			
9.	Clean wire heater with sandpaper, Scotch Brite and IPA			
10.	Use thin wire (step 3) to determine start and end position of wire heater on HX and clamp tool			
11.	Wrap wire heater in groove arou	nd HX and fix it with clamp tool, make sure hot section placed in groove		
12.	Measure resistance of wire heate	$r(R \approx 15 \Omega)$		
13.	Attach thermo couple on HX, on	the weld in middle, using kapton tape		
14.	Seal/protect section 2 with kapto	n, to prevent contamination with flux and solder		
15.	Place HX on hot plate, if needed a heat gun can be used to assist warming up HX.			
16.	Wait till temperature measured on HX T \approx 200 °C			
17.	With solder iron heat a small area of wire heater + HX (hot spot)			
18.	Apply flux with brush on hot spot and heat area again with solder iron			
19.	Apply solder to heated area			















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Test samp	le indication:	Test Date:	
Step	Action to be taken	Result	
20.	Repeat step 1719 on area just	next to previously heated area till wire heater completely soldered to HX	
21.	Slowly cool down HX, do NO	Cool with water	
22.	Clean solder section with brush	and IPA	
23.	Inspect joint for solder void, 'b	ad spot'	
24.	Repair bad spot		
25.	Place HX on hot plate		
26.	Wait till temperature measured	on HX T≈200 °C	
27.	With solder iron heat a bad spot of wire heater + HX (hot spot)		
28.	Apply flux with brush on hot spot and heat area again with solder iron		
29.	Apply solder to heated area		
30.	Repeat steps 27 29 for all 'ba	ad spots'	
31.	Slowly cool down HX, do NO	Cool with water	
32.	Measure resistance of wire hear	er ($R \approx 15 \Omega$)	
33.	Clean solder section with brush	, water and IPA	
34.	Section 2		
35.	Switch on hot plate, set $T \approx 250$		
36.	Measure length of wire heater and length of cold ends		
37.	Measure resistance of wire hear		
38.	Cut thin wire OD≤ 0.5 mm to le		
39.	Sandblast HX solder section 1,		
40.	Remove sand with compressed		















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Test samp	le indication:	Test engineer:	Test Date:
Step	Action to be taken		Result
41.	Clean groove with tissue and IPA		
42.	Clean wire heater with sandpaper,	Scotch Brite and IPA	
43.	Use thin wire (step 3) to determin	e start and end position of wire heater on HX and clamp tool	
44.	Wrap wire heater in groove aroun	d HX and fix it with clamp tool, make sure hot section placed in groove	
45.	Measure resistance of wire heater	$(R \approx 15 \Omega)$	
46.	Attach thermo couple on HX, on t	the weld in middle, using kapton tape	
47.	Place HX on hot plate, if needed a	heat gun can be used to assist warming up HX	
48.	Wait till temperature measured on	HX T≈200 °C	
49.	With solder iron heat a small ar	rea of wire heater + HX (hot spot)	
50.	Apply flux with brush on hot sp		
51.	Apply solder to heated area		
52.	Repeat step 4951 on area just ne	xt to previously heated area till wire heater completely soldered to HX	
53.	Slowly cool down HX, do NOT c	ool with water	
54.	Clean solder section with brush ar	nd IPA	
55.	Inspect joint for solder void, 'bad	spot'	
56.	Repair bad spot:		
57.	Place HX on hot plate		
58.	Wait till temperature measured on HX T \approx 200 °C		
59.	With solder iron heat a bad spot of wire heater + HX (hot spot)		
60.	Apply flux with brush on hot spot and heat area again with solder iron		
61.	Apply solder to heated area		















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Test sampl	e indication:	Test engineer:		Test Date:
Step	Action to be taken			Result
62.	Repeat step 59 61 for all 'bad spots'			
63.	Slowly cool down HX, do NOT cool with water			
64.	Measure resistance of wire heater ($R \approx 15 \Omega$)			
65.	Clean solder section with brush, water and IPA			















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